

Expect government approval for chip fab project in next 2 months: Darshan Hiranandani

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Real estate giant Hiranandani group, which is venturing into the semiconductor space through its company Tarq Semiconductors, expects an approval for its compound semiconductor fab project from the government in the next two months, Darshan Hiranandani, chief executive officer of the group, told FE in an interaction.

The company has submitted its applications for both an assembly, testing, marking, and packaging (ATMP) unit and compound semiconductor fab plant, which will come up in Uttar Pradesh. Compound semiconductors are critical for high-power and high temperature applications and products such as [LED](#), radio frequency devices, electronic devices, automobiles, etc. ATMP or chip assembly and packaging comes into play after semiconductor fabrication. It is the next step in the semiconductor value chain.

“We have already completed the application for ATMP as well as submitted our compound semiconductor fab project with the government. We expect to get all approvals from the government within the next 30 to 60 days,” Hiranandani said.